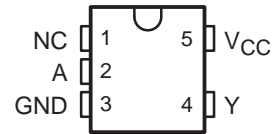


# SN74LVC1G06 SINGLE INVERTER BUFFER/DRIVER WITH OPEN-DRAIN OUTPUT

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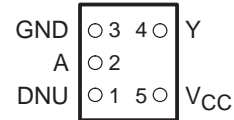
- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Supports 5-V  $V_{CC}$  Operation
- Input and Open-Drain Output Accept Voltages Up To 5.5 V
- Max  $t_{pd}$  of 4 ns at 3.3 V
- Low Power Consumption, 10- $\mu$ A Max  $I_{CC}$
- $\pm 24$ -mA Output Drive at 3.3 V
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE  
(TOP VIEW)



NC – No internal connection

YEA, YEP, YZA, OR YZP PACKAGE  
(BOTTOM VIEW)



DNU – Do not use

## description/ordering information

This single inverter buffer/driver is designed for 1.65-V to 5.5-V  $V_{CC}$  operation.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

The output of the SN74LVC1G06 device is open drain and can be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions. The maximum sink current is 32 mA.

## ORDERING INFORMATION

| $T_A$         | PACKAGE†   |              | ORDERABLE PART NUMBER | TOP-SIDE MARKING‡ |
|---------------|--|--------------|-----------------------|-------------------|
| –40°C to 85°C | NanoStar™ – WCSP (DSBGA)<br>0.17-mm Small Bump – YEA           | Reel of 3000 | SN74LVC1G06YEAR       | ---CT_            |
|               | NanoFree™ – WCSP (DSBGA)<br>0.17-mm Small Bump – YZA (Pb-free) |              | SN74LVC1G06YZAR       |                   |
|               | NanoStar™ – WCSP (DSBGA)<br>0.23-mm Large Bump – YEP           |              | SN74LVC1G06YEPR       |                   |
|               | NanoFree™ – WCSP (DSBGA)<br>0.23-mm Large Bump – YZP (Pb-free) |              | SN74LVC1G06YZPR       |                   |
|               | SOT (SOT-23) – DBV   | Reel of 3000 | SN74LVC1G06DBVR       | C06_              |
|               |  | Reel of 250  | SN74LVC1G06DBVT       |                   |
|               | SOT (SC-70) – DCK  | Reel of 3000 | SN74LVC1G06DCKR       | CT_               |
|               |  | Reel of 250  | SN74LVC1G06DCKT       |                   |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

‡ DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.

YEA/YZA, YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar and NanoFree are trademarks of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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# SN74LVC1G06

## SINGLE INVERTER BUFFER/DRIVER WITH OPEN-DRAIN OUTPUT

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### description/ordering information (continued)

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

FUNCTION TABLE

| INPUT<br>A | OUTPUT<br>Y |
|------------|-------------|
| H          | L           |
| L          | H           |

### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

|   |                 |
|---|-----------------|
| Supply voltage range, $V_{CC}$ .....  | -0.5 V to 6.5 V |
| Input voltage range, $V_I$ (see Note 1) .....   | -0.5 V to 6.5 V |
| Voltage range applied to any output in the high-impedance or power-off state, $V_O$<br>(see Note 1) ..... | -0.5 V to 6.5 V |
| Voltage range applied to any output in the high or low state, $V_O$<br>(see Notes 1 and 2) .....          | -0.5 V to 6.5 V |
| Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....   | -50 mA          |
| Output clamp current, $I_{OK}$ ( $V_O < 0$ ) .....  | -50 mA          |
| Continuous output current, $I_O$ .....  | $\pm 50$ mA     |
| Continuous current through $V_{CC}$ or GND .....  | $\pm 100$ mA    |
| Package thermal impedance, $\theta_{JA}$ (see Note 3): DBV package .....                                  | 206°C/W         |
| DCK package .....   | 252°C/W         |
| YEA/YZA package .....   | 154°C/W         |
| YEP/YZP package .....   | 132°C/W         |
| Storage temperature range, $T_{stg}$ .....  | -65°C to 150°C  |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The value of  $V_{CC}$  is provided in the recommended operating conditions table.  
3. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN74LVC1G06

## SINGLE INVERTER BUFFER/DRIVER WITH OPEN-DRAIN OUTPUT

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### recommended operating conditions (see Note 4)

|                 |                                    | MIN   | MAX                    | UNIT |      |
|-----------------|------------------------------------|---|------------------------|------|------|
| V <sub>CC</sub> | Supply voltage                     | Operating                                       | 1.65                   | 5.5  | V    |
|                 |                                    | Data retention only                             | 1.5                    |      |      |
| V <sub>IH</sub> | High-level input voltage           | V <sub>CC</sub> = 1.65 V to 1.95 V              | 0.65 × V <sub>CC</sub> |      | V    |
|                 |                                    | V <sub>CC</sub> = 2.3 V to 2.7 V                | 1.7                    |      |      |
|                 |                                    | V <sub>CC</sub> = 3 V to 3.6 V                  | 2                      |      |      |
|                 |                                    | V <sub>CC</sub> = 4.5 V to 5.5 V                | 0.7 × V <sub>CC</sub>  |      |      |
| V <sub>IL</sub> | Low-level input voltage            | V <sub>CC</sub> = 1.65 V to 1.95 V              | 0.35 × V <sub>CC</sub> |      | V    |
|                 |                                    | V <sub>CC</sub> = 2.3 V to 2.7 V                | 0.7                    |      |      |
|                 |                                    | V <sub>CC</sub> = 3 V to 3.6 V                  | 0.8                    |      |      |
|                 |                                    | V <sub>CC</sub> = 4.5 V to 5.5 V                | 0.3 × V <sub>CC</sub>  |      |      |
| V <sub>I</sub>  | Input voltage                      | 0   | 5.5                    | V    |      |
| V <sub>O</sub>  | Output voltage                     | 0   | 5.5                    | V    |      |
| I <sub>OL</sub> | Low-level output current           | V <sub>CC</sub> = 1.65 V                        | 4                      |      | mA   |
|                 |                                    | V <sub>CC</sub> = 2.3 V                         | 8                      |      |      |
|                 |                                    | V <sub>CC</sub> = 3 V                           | 16                     |      |      |
|                 |                                    |   | 24                     |      |      |
|                 |                                    | V <sub>CC</sub> = 4.5 V                         | 32                     |      |      |
| Δt/Δv           | Input transition rise or fall rate | V <sub>CC</sub> = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V | 20                     |      | ns/V |
|                 |                                    | V <sub>CC</sub> = 3.3 V ± 0.3 V                 | 10                     |      |      |
|                 |                                    | V <sub>CC</sub> = 5 V ± 0.5 V                   | 5                      |      |      |
| T <sub>A</sub>  | Operating free-air temperature     | -40   | 85                     | °C   |      |

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER        | TEST CONDITIONS          | V <sub>CC</sub>  | MIN             | TYP† | MAX  | UNIT |
|------------------|--------------------------|--|-----------------|------|------|------|
| V <sub>OL</sub>  | I <sub>OL</sub> = 100 μA | 1.65 V to 5.5 V  |                 |      | 0.1  | V    |
|                  | I <sub>OL</sub> = 4 mA   | 1.65 V   |                 |      | 0.45 |      |
|                  | I <sub>OL</sub> = 8 mA   | 2.3 V  |                 |      | 0.3  |      |
|                  | I <sub>OL</sub> = 16 mA  | 3 V  |                 |      | 0.4  |      |
|                  |                          |  |                 |      | 0.55 |      |
|                  | I <sub>OL</sub> = 32 mA  | 4.5 V  |                 |      | 0.55 |      |
| I <sub>I</sub>   | A input                  | V <sub>I</sub> = 5.5 V or GND  | 0 to 5.5 V      |      | ±5   | μA   |
| I <sub>off</sub> |                          | V <sub>I</sub> or V <sub>O</sub> = 5.5 V                                     | 0               |      | ±10  | μA   |
| I <sub>CC</sub>  |                          | V <sub>I</sub> = 5.5 V or GND, I <sub>O</sub> = 0                            | 1.65 V to 5.5 V |      | 10   | μA   |
| ΔI <sub>CC</sub> |                          | One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND | 3 V to 5.5 V    |      | 500  | μA   |
| C <sub>i</sub>   |                          | V <sub>I</sub> = V <sub>CC</sub> or GND                                      | 3.3 V           |      | 4    | pF   |
| C <sub>o</sub>   |                          | V <sub>O</sub> = V <sub>CC</sub> or GND                                      | 3.3 V           |      | 5    | pF   |

† All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.



**SN74LVC1G06**  
**SINGLE INVERTER BUFFER/DRIVER**  
**WITH OPEN-DRAIN OUTPUT**

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

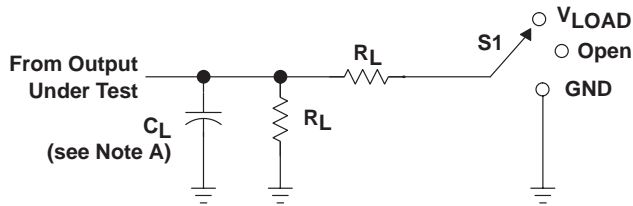
| PARAMETER       | FROM (INPUT) | TO (OUTPUT) | V <sub>CC</sub> = 1.8 V ± 0.15 V |     | V <sub>CC</sub> = 2.5 V ± 0.2 V |     | V <sub>CC</sub> = 3.3 V ± 0.3 V |     | V <sub>CC</sub> = 5 V ± 0.5 V |     | UNIT |
|-----------------|--------------|-------------|----------------------------------|-----|---------------------------------|-----|---------------------------------|-----|-------------------------------|-----|------|
|                 |              |             | MIN                              | MAX | MIN                             | MAX | MIN                             | MAX | MIN                           | MAX |      |
| t <sub>pd</sub> | A            | Y           | 2.2                              | 6.5 | 1.1                             | 4   | 1.2                             | 4   | 1                             | 3   | ns   |

operating characteristics, T<sub>A</sub> = 25°C

| PARAMETER                                     | TEST CONDITIONS | V <sub>CC</sub> = 1.8 V | V <sub>CC</sub> = 2.5 V | V <sub>CC</sub> = 3.3 V | V <sub>CC</sub> = 5 V | UNIT |
|---|-----------------|-------------------------|-------------------------|-------------------------|-----------------------|------|
|   |                 | TYP                     | TYP                     | TYP                     | TYP                   |      |
| C <sub>pd</sub> Power dissipation capacitance | f = 10 MHz      | 3                       | 3                       | 4                       | 6                     | pF   |



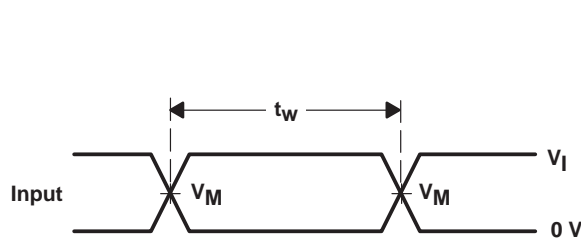
**PARAMETER MEASUREMENT INFORMATION**  
**(OPEN DRAIN)**



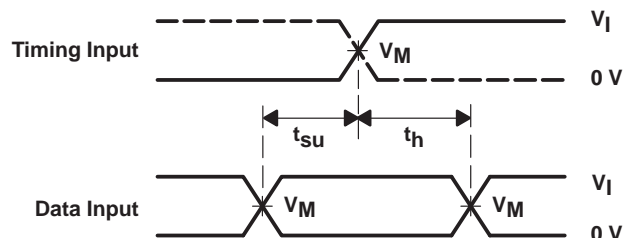
| TEST                     | S1                |
|--------------------------|-------------------|
| tpZL (see Notes E and F) | V <sub>LOAD</sub> |
| tpLZ (see Notes E and G) | V <sub>LOAD</sub> |
| tPHZ/tPZH                | V <sub>LOAD</sub> |

**LOAD CIRCUIT**

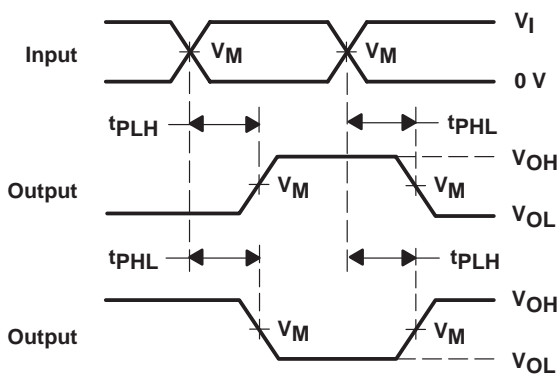
| V <sub>CC</sub> | INPUT           |                                | V <sub>M</sub>     | V <sub>LOAD</sub>   | C <sub>L</sub> | R <sub>L</sub> | V <sub>Δ</sub> |
|-----------------|-----------------|--------------------------------|--------------------|---------------------|----------------|----------------|----------------|
|                 | V <sub>I</sub>  | t <sub>r</sub> /t <sub>f</sub> |                    |                     |                |                |                |
| 1.8 V ± 0.15 V  | V <sub>CC</sub> | ≤ 2 ns                         | V <sub>CC</sub> /2 | 2 × V <sub>CC</sub> | 30 pF          | 1 kΩ           | 0.15 V         |
| 2.5 V ± 0.2 V   | V <sub>CC</sub> | ≤ 2 ns                         | V <sub>CC</sub> /2 | 2 × V <sub>CC</sub> | 30 pF          | 500 Ω          | 0.15 V         |
| 3.3 V ± 0.3 V   | 3 V             | ≤ 2.5 ns                       | 1.5 V              | 6 V                 | 50 pF          | 500 Ω          | 0.3 V          |
| 5 V ± 0.5 V     | V <sub>CC</sub> | ≤ 2.5 ns                       | V <sub>CC</sub> /2 | 2 × V <sub>CC</sub> | 50 pF          | 500 Ω          | 0.3 V          |



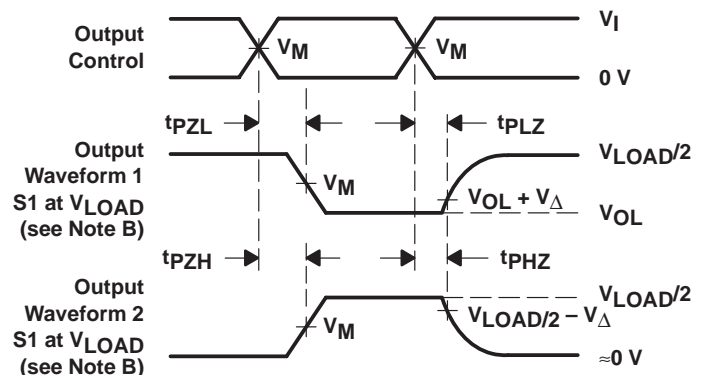
**VOLTAGE WAVEFORMS**  
**PULSE DURATION**



**VOLTAGE WAVEFORMS**  
**SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS**  
**PROPAGATION DELAY TIMES**  
**INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS**  
**ENABLE AND DISABLE TIMES**  
**LOW- AND HIGH-LEVEL ENABLING**

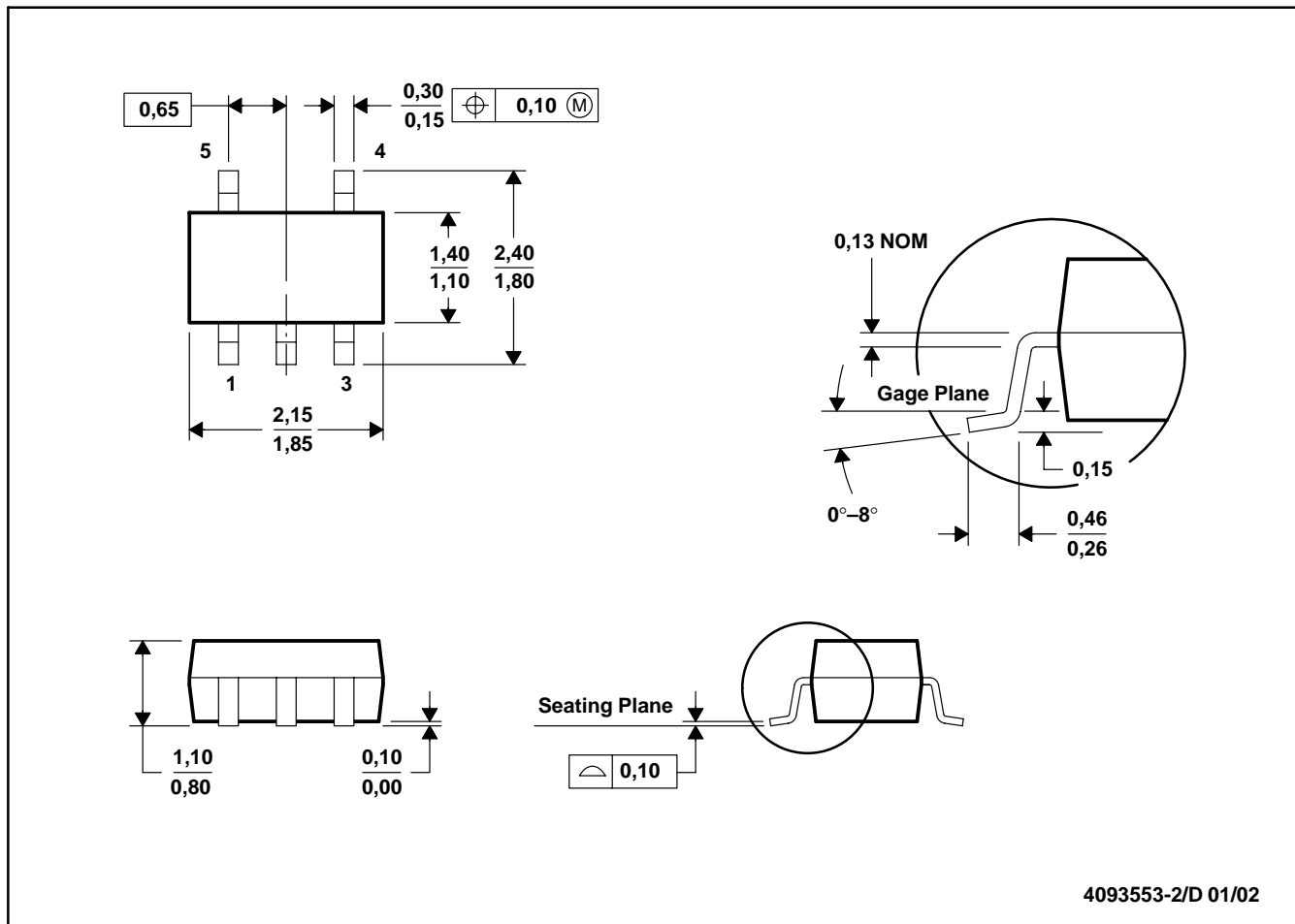
- NOTES:
- C<sub>L</sub> includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω.
  - The outputs are measured one at a time with one transition per measurement.
  - Since this device has open-drain outputs, t<sub>PZL</sub> and t<sub>PLZ</sub> are the same as t<sub>pd</sub>.
  - t<sub>PZL</sub> is measured at V<sub>M</sub>.
  - t<sub>PLZ</sub> is measured at V<sub>OL</sub> + V<sub>Δ</sub>.
  - All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**



DCK (R-PDSO-G5)

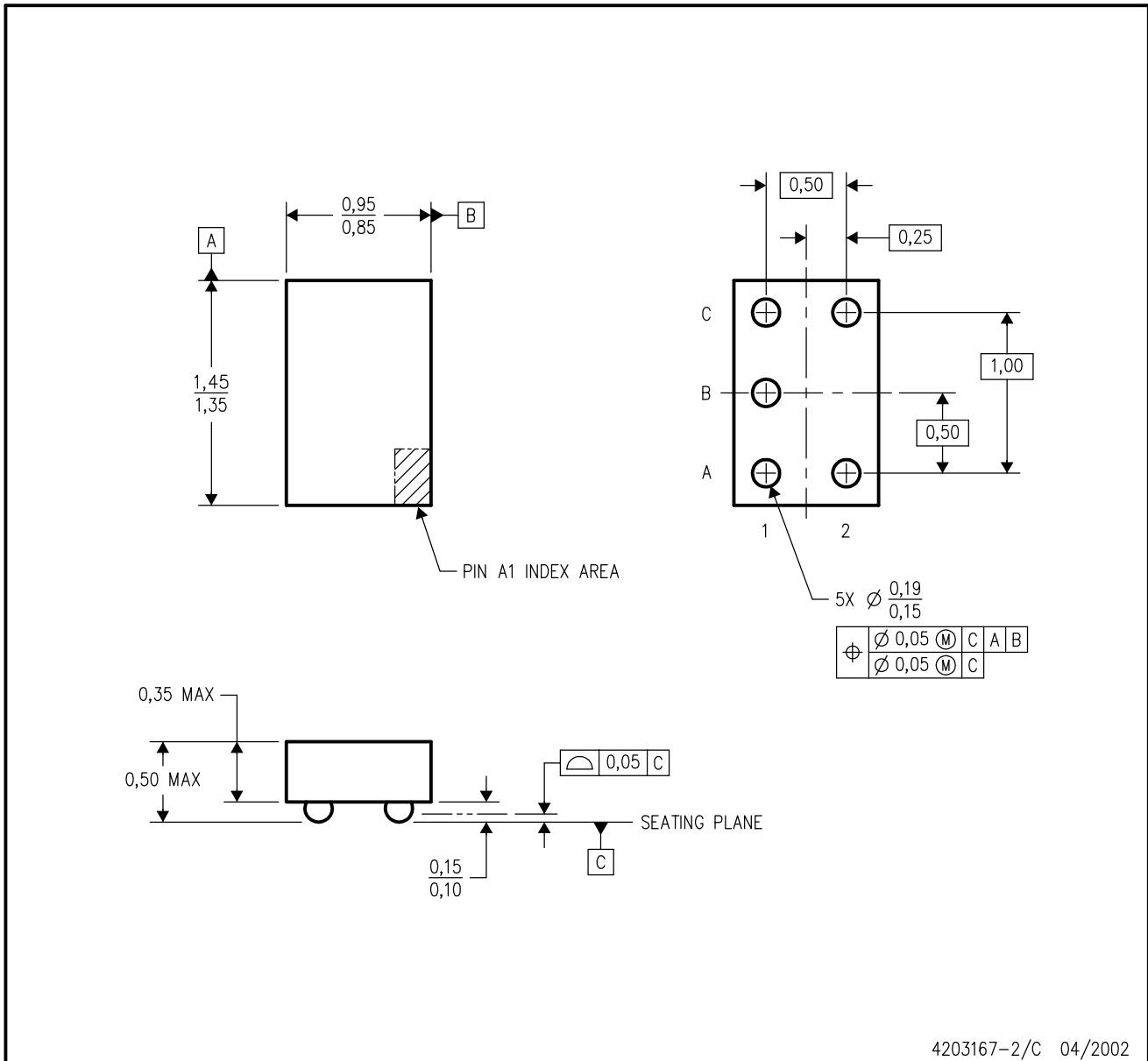
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion.  
 D. Falls within JEDEC MO-203

YEA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY

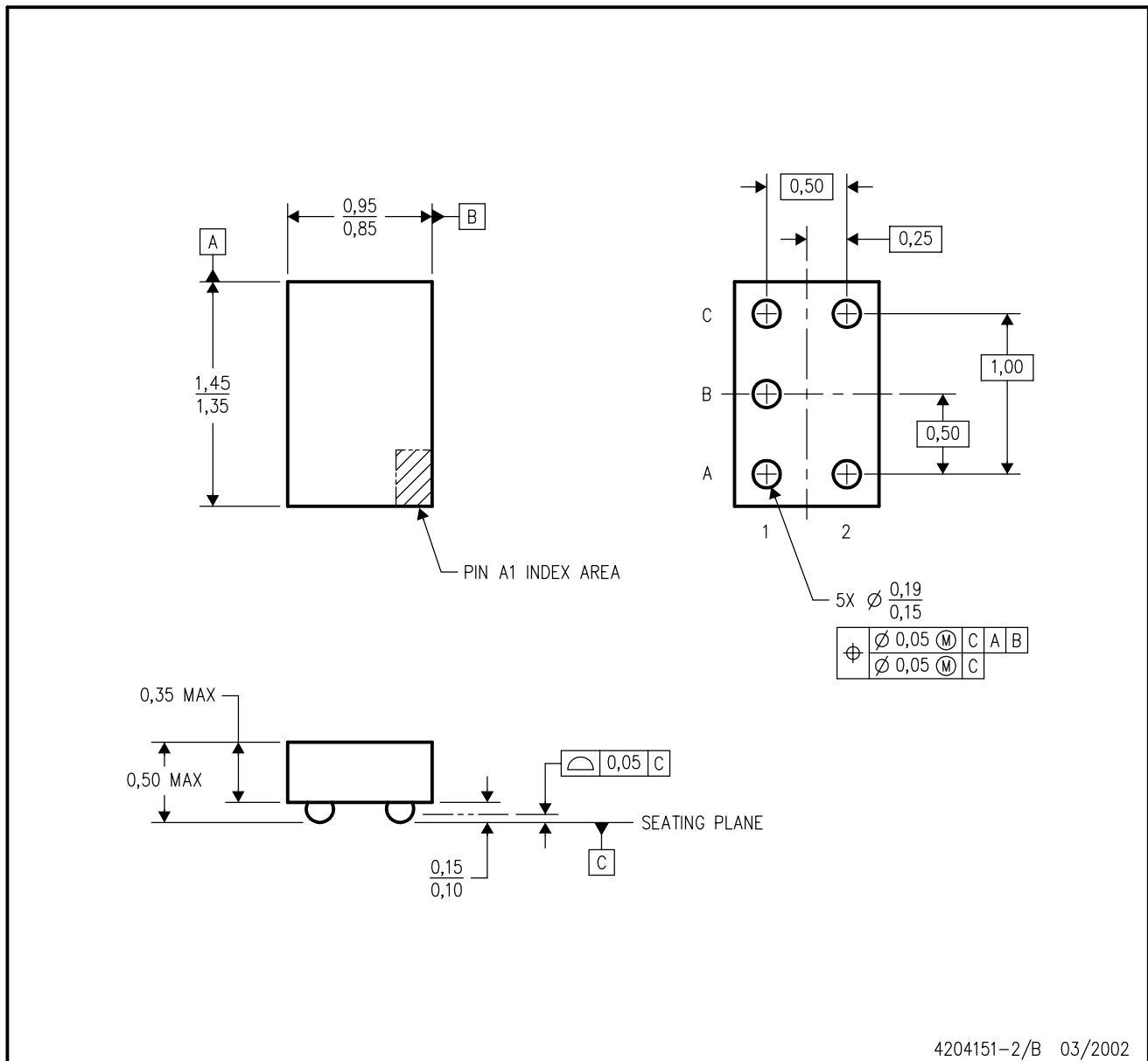


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoStar™ package configuration.
  - D. Package complies to JEDEC MO-211 variation EA.
  - E. This package is tin-lead (SnPb). Refer to the 5 YZA package (drawing 4204151) for lead-free.

NanoStar is a trademark of Texas Instruments.

YZA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY

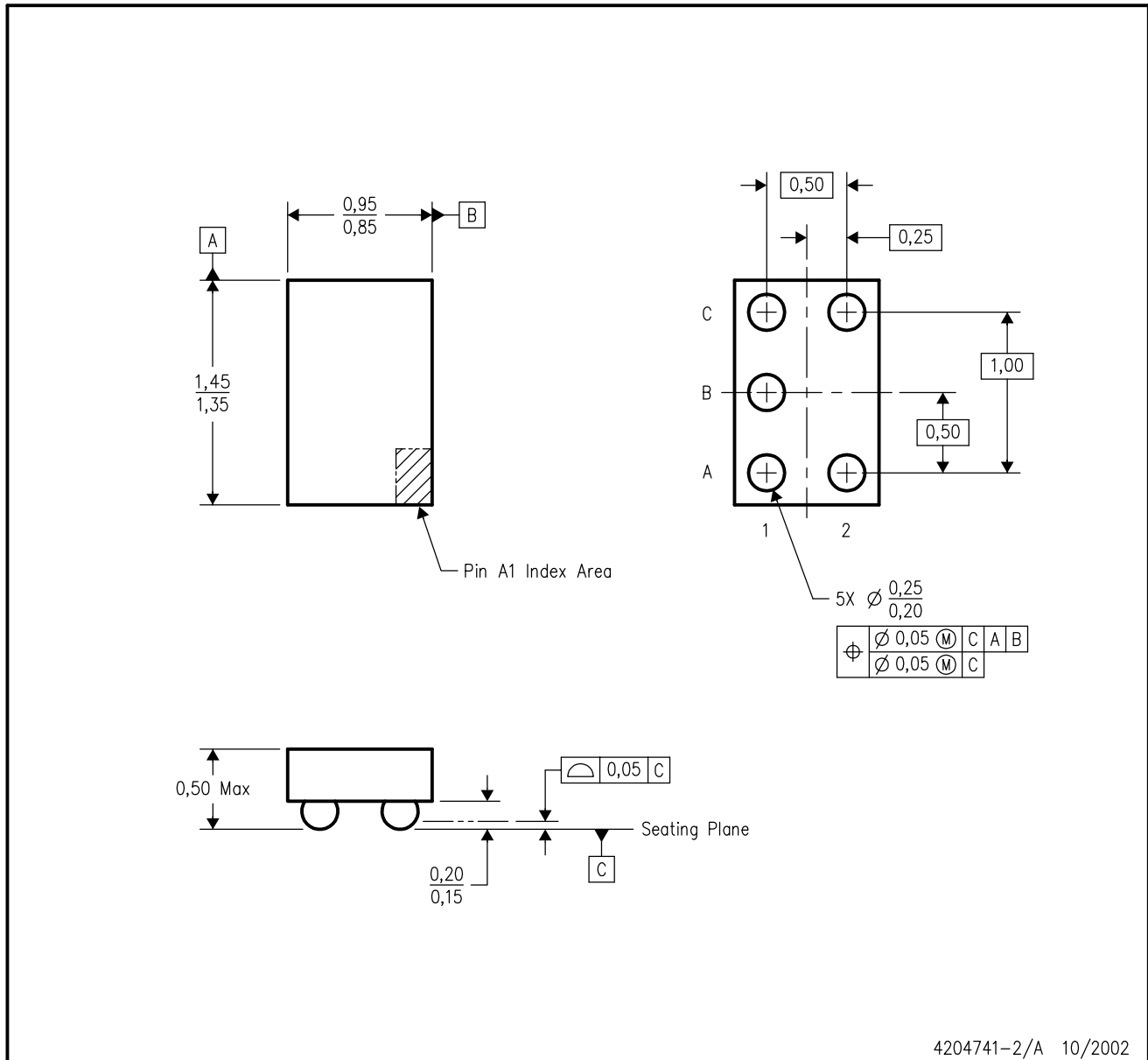


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.
  - D. Package complies to JEDEC MO-211 variation EA.
  - E. This package is lead-free. Refer to the 5 YEA package (drawing 4203167) for tin-lead (SnPb).

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YZP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY

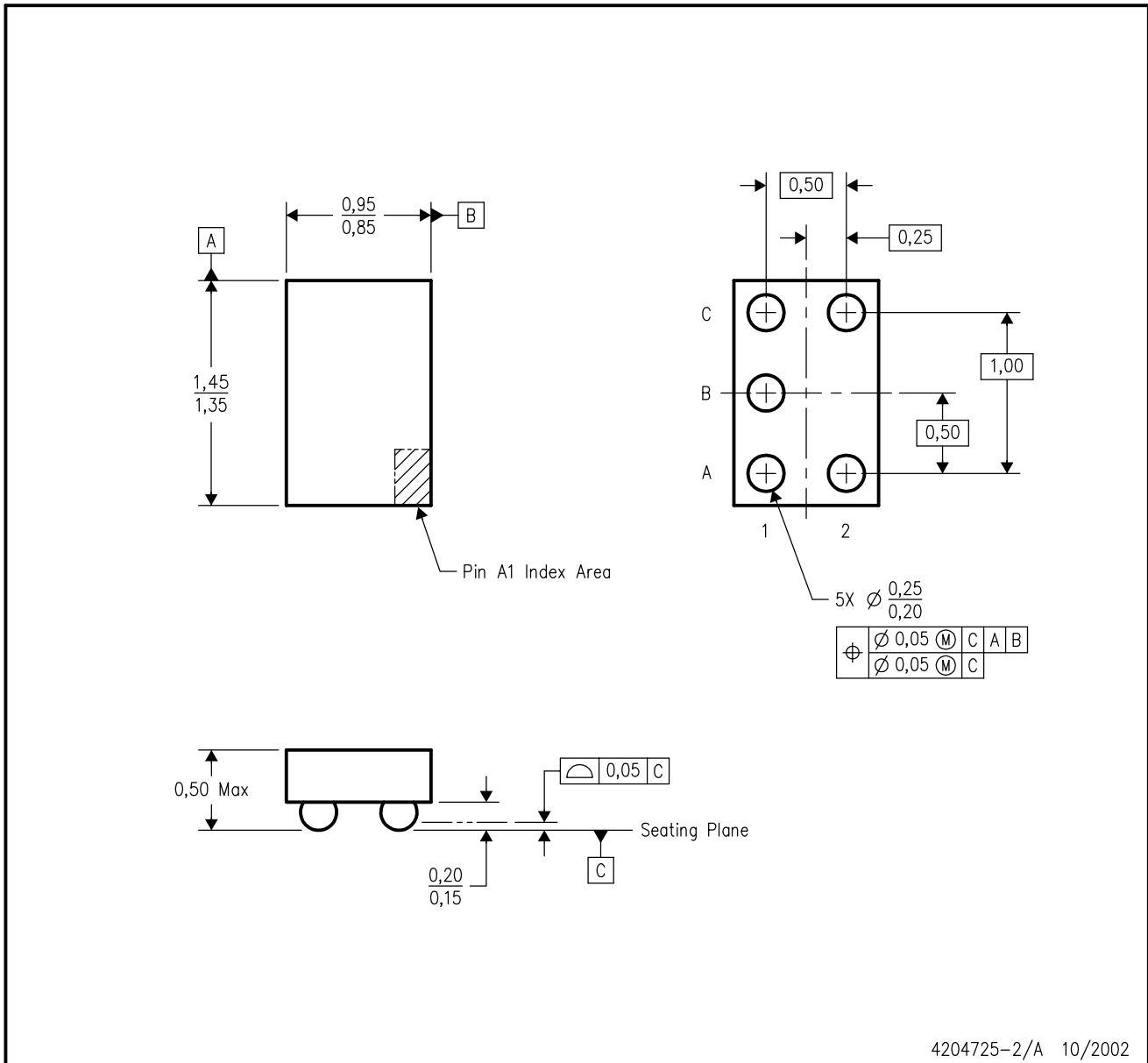


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.
  - D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.

YEP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoStar™ package configuration.
  - D. This package is tin-lead (SnPb). Refer to the 5 YZP package (drawing 4204741) for lead-free.

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